

(Page 13, lines 1-26):

thereafter attach the resin sheet having the marking to the rear surface of the wafer.

Thereby, the marking information including the position information and result of electrical test is not required to temporarily print unlike the first embodiment and the result of electrical test can be marked on the resin sheet simultaneously when the test is performed.

Moreover, it is also possible to previously print the numerals and codes indicating the position information of the chip on the resin sheet and then attaching the resin sheet to the rear surface of wafer under the condition of Fig.2(a). In this case, the result of electrical test is not printed. The result of electrical test is no longer required to print on the resin sheet in the case where such result is stored in the memory together with the position information of chip. Thereby, the marking process of the test result may be omitted and accordingly the processes may be saved.

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[Effect of the Invention]

As explained above, according to the method of manufacturing wafer level semiconductor device of the present invention, since the information indicating where the internal chips are located on the wafer can be printed on the diced semiconductor package, the trace-ability of search for defective product can be very much improved.

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What is claimed is:

1. A method of manufacturing wafer level semiconductor device, comprising the steps